Intel's SECC2 Packaging

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Objective

Provide a consolidated summary and reference of available SECC2 enabling information.

Detailed information pertaining to items described in the presentation will be posted to this website as it becomes available.





Intel Performance PC Package Transition





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SECC2 Transition Timeframe

- λ Per PCN #685, Pentium[®] II 350MHz PLGA core processor became available in the SECC2-PLGA form factor in Nov '98
 - σ PCN #685 available in the PCN Index on http://developer.intel.com/design/pcn/IA/index.htm
- λ Per PCN #723REV2, Pentium II 400MHz/450MHz converts to SECC2 as well
 - $\sigma~$ 400MHz available in SECC2-PLGA and SECC2-OLGA
 - σ 450MHz only available in SECC2-OLGA
 - σ PCN #723 available in the PCN Index on http://developer.intel.com/design/pcn/IA/index.htm
- λ Motherboards readiness requires a new retention module:
 - σ Intel enabled a Universal Retention Module (URM) for SEPP, SECC, & SECC2
 - σ The Intel[®] Celeron[™] processor Retention Module is also SECC2 capable
- λ New heat sink required for SECC2
- λ SECC will maintain very limited availability through '99 at a price premium
 - $\sigma~$ SECC product discontinuance notification planned in Q2 '99



SECC2 Package

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• Two versions (PLGA version is limited)



OLGA

- PLGA SECC2 and OLGA SECC2 each require unique heatsink
- Same clip, retention mechanism, thermal interface material, and assembly/disassembly tools





PLGA/OLGA Heat Sink Differences



Thermal Metrology varies. See Pentium[®] II processor datasheet on developer.intel.com Order Number 243657-003

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Heat Sink Clip



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- Intel has enabled this heat sink clip.
- See the "Support Components" on developer.intel.com for suppliers



Active Heat Sinks

- A boxed processor is also available which is complete with active heatsink
 - ▲ See Pentium® II processor datasheet on developer.intel.com
 - Order Number 243657-003
- Active Heat Sink solutions are being enabled
 - ▲ Watch "Support Components" on developer.intel.com for suppliers
 - PLGA solution uses custom heat sink attach process
 - OLGA solution requires plastic clips
- Active Heat Sink Clips
 - ▲ Intel has developed a clip for use with active heatsinks as well
 - ▲ Watch "Support Components" on developer.intel.com for suppliers



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URM, S.E.P.P., S.E.C.C. Retention Mechanisms

 Consider the amount of the retention mechanism flex when designing motherboard layout



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SECC2 Heat Sink Assembly Fixture



Vendor : Napco

Designed only for the Intel-enabled clips for both PLGA and OLGA SECC2 packages





SECC2 Heat Sink Disassembly Fixture

Vendor : Napco







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Intel Processor Packaging Summary Table

	SECC	SECC2	SEPP	PPGA
Heat sink	ATXV2	SECC2 Heat sink	SEPP only H/S	PPGA H/S
Weight	237 grams	130 grams	130 grams	85 grams
Dissipation	40 Watts	36 Watts	20 Watts	35 Watts
Attach	Interfaces with	Substrate holes	Substrate holes	Attaches to top of
Locations	thermal plate			component
Connector	SC242	SC 242	SC 242	PGA370 Socket
Heat sink support	Required	Not Required	Not Required	Not applicable
Retention	Universal RM	Universal RM	Universal RM	Not applicable
Mechanism	Standard RM	Intel [®] Celeron [™] RM	Intel Celeron RM	
Support	Integrated RM			
Heat sink Clip	Riv screws	SECC2 H/S Clip	Intel Celeron SEPP H/S clips	Similar to Socket 7
Thermal Interface	Various	Chomerics 443	Chomerics 7-10	Chomerics 443
Options		Thermal Grease	Thermal Grease	Thermal Grease
RMAM's	Required with metal	Required with metal	Required with metal	Not applicable
	fastener RM	fastener RM	fastener RM	

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